

Product / Package Information

Package	PDIP
Body Size	300 mils
Lead Count	18
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Percentage (%)	Component Level	PPM
				Percentage (%)	PPM			
Other inorganic materials	Silica	60676-86-0	7.94 E-01	87.7	877000	59.88		598809
Thermosets	Epoxy Resin	Proprietary	4.53 E-02	5.0	50000	3.41		34140
Thermosets	Phenol Resin	Proprietary	4.53 E-02	5.0	50000	3.41		34140
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.81 E-02	2.0	20000	1.37		13656
Other inorganic materials	Carbon Black	1333-86-3	2.72 E-03	0.3	3000	0.20		2048
Subtotal			9.06 E-01	100	1000000	68.28		682793

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Percentage (%)	Component Level	PPM
				Percentage (%)	PPM			
Copper & its alloys	Copper	7440-50-8	3.81 E-01	97.57	975706	28.71		287077
Copper & its alloys	Iron	7439-89-6	8.90 E-03	2.28	22789	0.67		6705
Copper & its alloys	Zinc	7440-66-6	4.93 E-04	0.13	1263	0.04		372
Copper & its alloys	Phosphorus	7723-14-0	9.46 E-05	0.02	242	0.01		71
Subtotal			3.90 E-01	100.00	1000000	29.42		294225

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Percentage (%)	Component Level	PPM
				Percentage (%)	PPM			
Precious metals	Silver	7440-22-4	9.30 E-04	100.0	1000000	0.07		701

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Percentage (%)	Component Level	PPM
				Percentage (%)	PPM			
Tin & its alloys	Tin	7440-31-5	2.06 E-02	100.0	1000000	1.55		15543

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Percentage (%)	Component Level	PPM
				Percentage (%)	PPM			
Precious metals	Gold	7440-57-5	9.40 E-04	99.99	1000000	0.07		709

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Percentage (%)	Component Level	PPM
				Percentage (%)	PPM			
Other inorganic materials	Doped Silicon	7440-21-3	5.90 E-03	100.0	1000000	0.44		4447

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Percentage (%)	Component Level	PPM
				Percentage (%)	PPM			
Precious metals	Silver	7440-22-4	1.49 E-03	73.40	734000	0.11		1123
Thermoset	Epoxy Resin	Proprietary	3.73 E-04	18.35	183500	0.03		281
Other inorganic materials	Metal oxide	Proprietary	5.58 E-05	2.75	27500	0.004		42
Others	Curing and hardening agent	Proprietary	5.58 E-05	2.75	27500	0.004		42
Other organic materials	Gamma Butyrolactone	96-48-0	5.58 E-05	2.75	27500	0.004		42
Subtotal			2.03 E-03	100.00	1000000	0.15		1530

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Percentage (%)	Component Level	PPM
				Percentage (%)	PPM			
Other organic materials	Dimethylsiloxane	68083-19-2	4.23 E-05	60.4	604000	0.003		32
Other organic materials	Dimethylvinylated & Trimethylated silica	68988-89-6	1.96 E-05	28.0	280000	0.001		15
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	7.00 E-06	10.0	100000	0.001		5
Other organic materials	Ethylbenzene	100-41-4	7.00 E-07	1.0	10000	0.00005		1
Other organic materials	Xylene	1330-20-7	4.20 E-07	0.6	6000	0.00003		0.3
Subtotal			7.00 E-05	100.0	1000000	0.01		53

Package Totals	Weight (g)	Percentage (%)	PPM
	1.33 E+00	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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